WIRE WOUND CHIP INDUCTORS SWI1008CT SERIES

Introductions

The SWI series are wire wound chip inductors widely used in the communication applications.
The wire wound inductors advance in higher self resonate frequency, better Q factor and much more stable performance. Precious tolerance of 2% is available.

Features

* Operating temperature -40 to +125°C.
* Excellent solderability and resistance to soldering heat.
* Suitable for reflow soldering.
* High reliability and easy surface mount assembly.
* Wide range of inductance values are available for flexible needs.

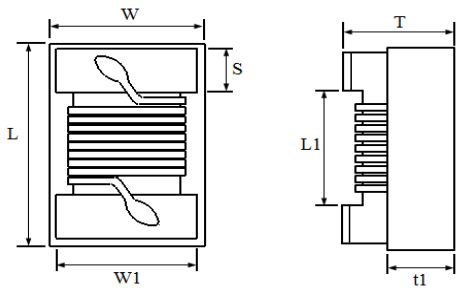
Part Number Code

SWI 1008 C T 33N J - □□

1 2 3 taping 4 5 6

1 Product Type

2 Chip Dimension



Size (inch) mm	Length (L) (inch) mm	Width (W) (inch) mm	Thickness (T) (inch) mm	Terminal (S) (inch) mm	L1 (Ref.) mm	W1 (Ref.) mm	(t1) (Ref.) mm
SWI 1008 2520	(0.102 ± 0.008) 2.60 ± 0.20	(0.083 ± 0.008) 2.10 ± 0.20	(0.067 ± 0.008) 1.70 ± 0.20	(0.020 ± 0.004) 0.50 ± 0.10	1.40	1.90	0.70

3 Material Type C : Ceramic Material

4 Inductance Value 3N3 = 3.3nH 33N = 33nH R33 = 330nH 1R0 = 1.0μH

5 Tolerance B = ±0.20 nH G = ±2% K = ±10%
S = ±0.30 nH J = ±5%

6 Internal Code If any

CHIP INDUCTOR SPECIFICATIONS

1. Scope

This specification applies to fixed inductors of the following types used in electronic equipment.

Ceramic Type : For lower inductance with high Q factor at high frequency and stable circuit requirement.

2. Construction

Configuration & Dimension : Please refer to the attached figures and tables.

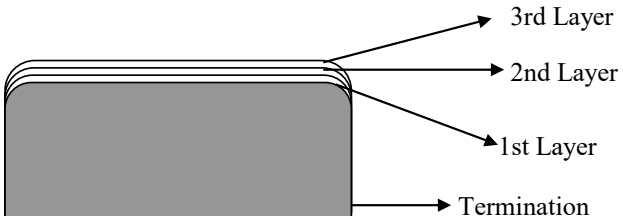
Terminals : The terminals shall consist of Ag alloy followed by Nickel, then Gold plating for easier soldering.

3. Operating Temperature Range

Operating Temperature Range is the scope of ambient temperature at which the inductor can be operated continuously at rated current.

Temp. Range : -40°C to +125°C

4. Ingredient of terminals electrode



a) 1st layer : Ag
b) 2nd layer : Ni
c) 3rd layer : Au

5. Characteristics

Standard Atmospheric Conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurements and tests are as follows :

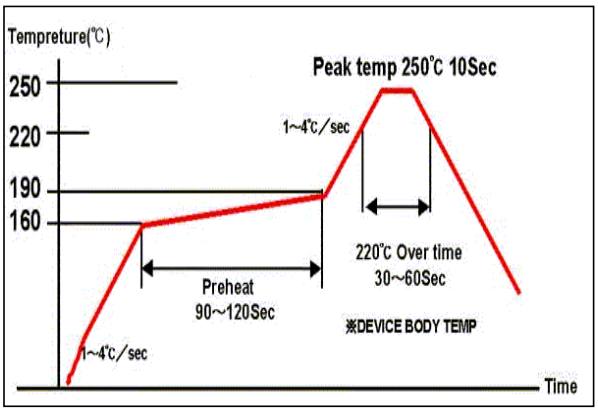
Ambient Temperature : 25°C ± 2°C

Relative Humidity : 60% to 70%

Air Pressure : 86 kPa to 106 kPa

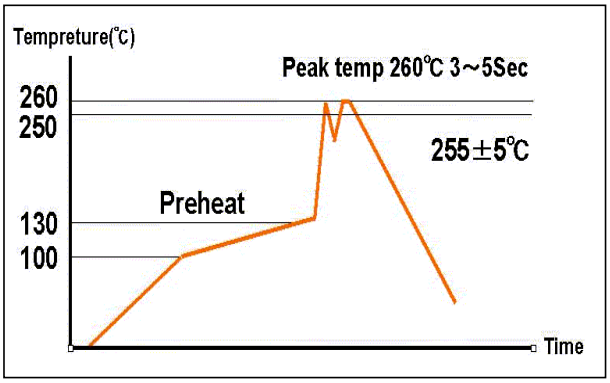
Temperature profile

a. Reflow temperature profile
(Temperature of the mounted parts surface on the printed circuit board)



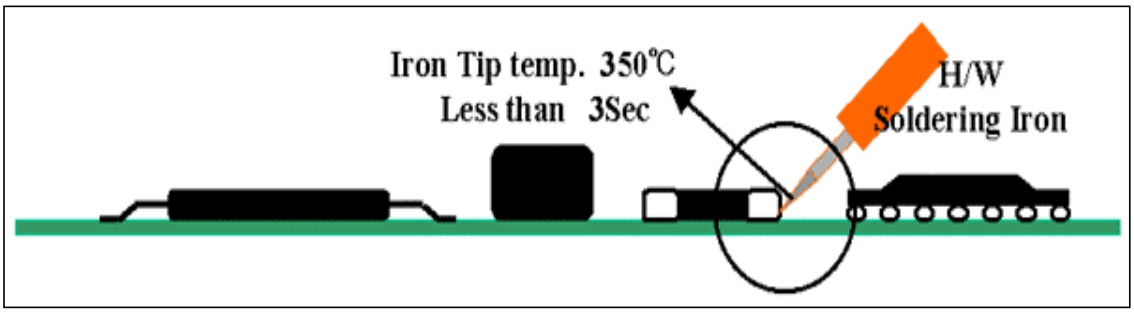
Recommended Peak Temperature：250°C Max
250°C up /within 10secs
Max. Reflow temperature : 260°C.
Gradient of temperature rise：av 1-4°C/sec
Preheat：160-190°C/within 90-120secs
220°C up /within 30-60secs
Composition of solder Sn-3Ag-0.5Cu

b. Dip temperature



Solder bathtub temperature: 260°C max.
within 5secs.
Preheating temperature: 100～130°C
deposit solder temperature.
Composition of solder Sn-3Ag-0.5Cu

c. Soldering iron tip temperature : 350°C max / within 3 seconds.



CHIP INDUCTOR
WIRE WOUND TYPE

SWI1008 (2520) CERAMIC SERIES

Specification

Part No.	Inductance [1] (nH)	Percent Tolerance	Q [2] Min	S.R.F. [3] Min (MHz)	RDC [4] Max (Ω)	IDC [5] Max (mA)	Marking
SWI1008CT3N3 □-□□	3.3 @ 100MHz	B, S	50 @ 1000MHz	6000	0.06	1000	3N3
SWI1008CT6N8 □-□□	6.8 @ 100MHz	B, S	50 @ 1000MHz	5500	0.06	1000	6N8
SWI1008CT8N2 □-□□	8.2 @ 100MHz	B, S	50 @ 1000MHz	5500	0.06	1000	8N2
SWI1008CT10N □-□□	10 @ 100MHz	B, S	50 @ 1000MHz	4300	0.08	1000	10N
SWI1008CT12N □-□□	12 @ 100MHz	B, S	60 @ 500MHz	3600	0.08	1000	12N
SWI1008CT15N □-□□	15 @ 100MHz	K, J, B	60 @ 500MHz	2700	0.08	1000	15N
SWI1008CT18N □-□□	18 @ 100MHz	K, J, B	60 @ 350MHz	2700	0.10	1000	18N
SWI1008CT22N □-□□	22 @ 100MHz	K, J, B	60 @ 350MHz	2500	0.10	1000	22N
SWI1008CT27N □-□□	27 @ 100MHz	K, J, B	60 @ 350MHz	1800	0.10	1000	27N
SWI1008CT33N □-□□	33 @ 100MHz	K, J, G	60 @ 350MHz	1700	0.10	1000	33N
SWI1008CT39N □-□□	39 @ 100MHz	K, J, G	60 @ 350MHz	1500	0.10	1000	39N
SWI1008CT47N □-□□	47 @ 100MHz	K, J, G	60 @ 350MHz	1500	0.10	1000	47N
SWI1008CT56N □-□□	56 @ 100MHz	K, J, G	60 @ 350MHz	1350	0.12	1000	56N
SWI1008CT68N □-□□	68 @ 100MHz	K, J, G	60 @ 350MHz	1300	0.15	1000	68N
SWI1008CT82N □-□□	82 @ 100MHz	K, J, G	60 @ 350MHz	1100	0.18	1000	82N
SWI1008CTR10 □-□□	100 @ 100MHz	K, J, G	60 @ 350MHz	1100	0.18	1000	R10
SWI1008CTR12 □-□□	120 @ 25.2MHz	K, J, G	45 @ 100MHz	950	0.20	800	R12
SWI1008CTR15 □-□□	150 @ 25.2MHz	K, J, G	45 @ 100MHz	880	0.22	800	R15
SWI1008CTR18 □-□□	180 @ 25.2MHz	K, J, G	45 @ 100MHz	800	0.33	800	R18
SWI1008CTR22 □-□□	220 @ 25.2MHz	K, J, G	45 @ 100MHz	730	0.45	800	R22
SWI1008CTR27 □-□□	270 @ 25.2MHz	K, J, G	45 @ 100MHz	650	0.75	600	R27
SWI1008CTR29 □-□□	290 @ 25.2MHz	K, J, G	45 @ 100MHz	600	0.60	600	-
SWI1008CTR33 □-□□	330 @ 25.2MHz	K, J, G	45 @ 100MHz	570	0.90	500	R33
SWI1008CTR39 □-□□	390 @ 25.2MHz	K, J, G	45 @ 100MHz	530	1.06	470	R39
SWI1008CTR47 □-□□	470 @ 25.2MHz	K, J, G	45 @ 100MHz	480	1.17	420	R47
SWI1008CTR56 □-□□	560 @ 25.2MHz	K, J, G	45 @ 100MHz	430	1.50	310	R56
SWI1008CTR68 □-□□	680 @ 25.2MHz	K, J, G	45 @ 100MHz	380	2.06	230	R68
SWI1008CTR75 □-□□	750 @ 25.2MHz	K, J, G	45 @ 100MHz	360	2.20	200	R75
SWI1008CTR82 □-□□	820 @ 25.2MHz	K, J, G	45 @ 100MHz	350	2.30	180	R82
SWI1008CTR91 □-□□	910 @ 25.2MHz	K, J, G	45 @ 100MHz	330	3.18	150	R91
SWI1008CT1R0 □-□□	1000 @ 25.2MHz	K, J, G	35 @ 50MHz	310	3.30	120	1R0
SWI1008CT1R2 □-□□	1200 @ 7.96MHz	K, J	25 @ 50MHz	150	2.70	110	1R2
SWI1008CT1R8 □-□□	1800 @ 7.96MHz	K, J	30 @ 50MHz	150	4.50	100	1R8
SWI1008CT3R9 □-□□	3900 @ 7.96MHz	K, J	25 @ 50MHz	140	9.70	100	3R9

1. Inductance is measured in HP-4287A RF LCR meter with HP-16193 test fixture.
2. Q is measured in HP-4287A RF LCR meter with HP-16193 test fixture.
3. SRF is measured in ENA E5071B network analyzer or equivalent.
4. RDC is measured in HP-4338B milliohm meter or equivalent.
5. For 15 °C Rise.

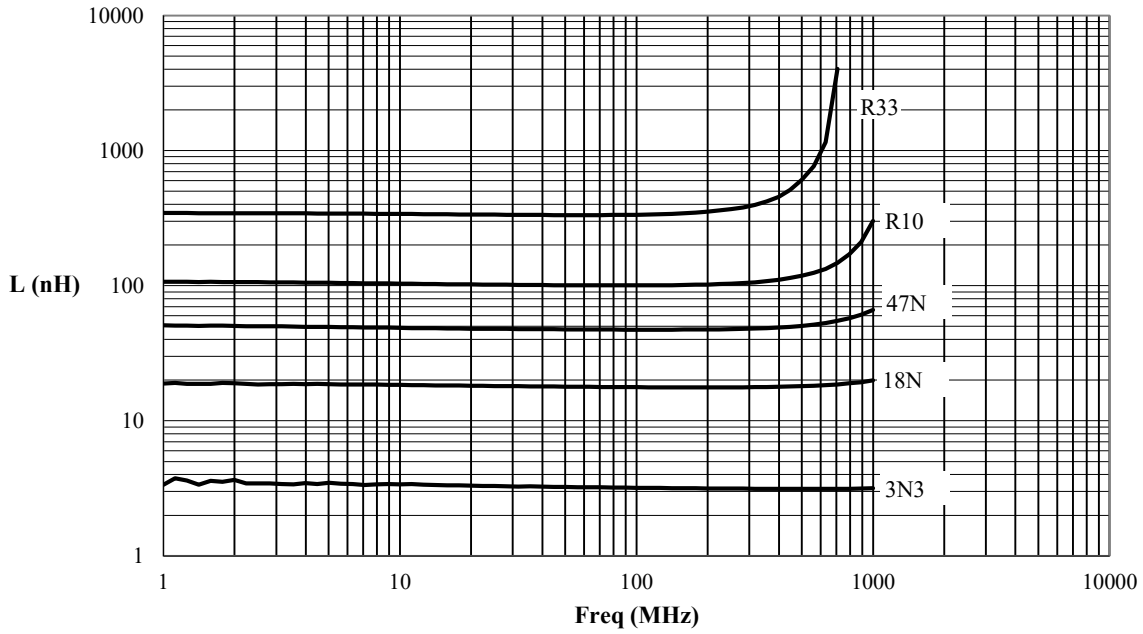
Unit weight = 0.025g (for ref.)

CHIP INDUCTOR
WIRE WOUND TYPE

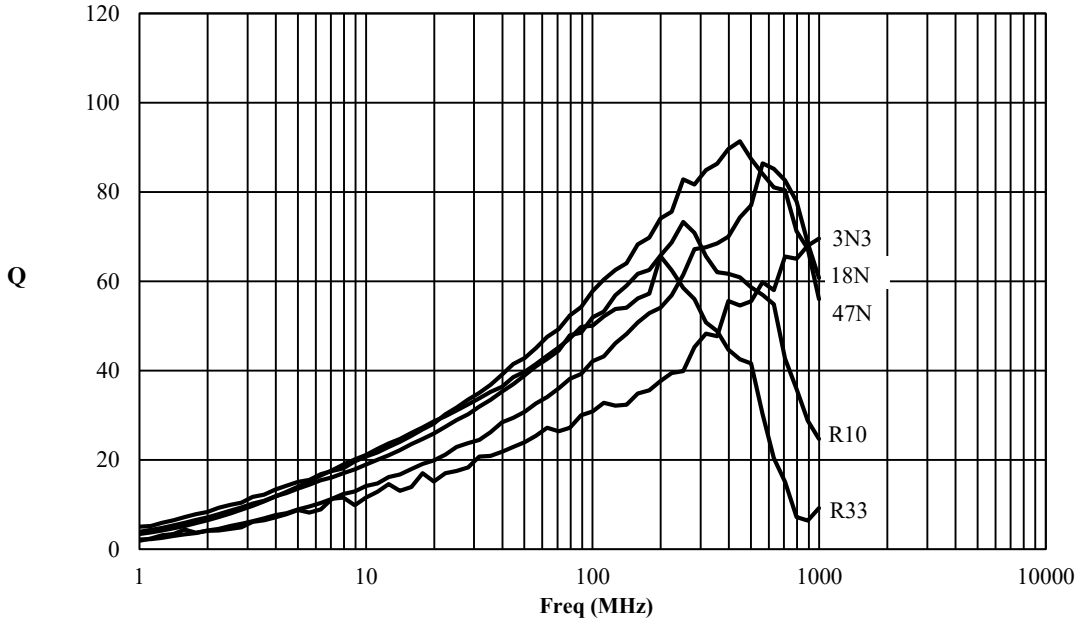
SWI1008 (2520) CERAMIC SERIES

Specification

L vs Freq Plot



Q vs Freq Plot



RELIABILITY TEST

ITEM		CONDITION	SPECIFICATION
Electrical Characteristics	Inductance and Tolerance	Measuring Frequency : As shown in Product Table Measuring Temperature : + 25 °C	Within Specified Tolerance
	Quality Factor		
	Insulation Resistance	Measured at 100V DC between inductor terminals and center of case.	1000 mega ohms minimum
	Dielectric Withstanding Voltage	Measured at 500V AC between inductor terminals and center of case for a maximum of 1 minute.	No damage occurs when the test voltage is applied.
	Temperature Coefficient of Inductance (TCL)	Over -40°C to +85°C at frequency specified in Product Table.	+ 25 to 500 ppm / °C TCL = $\frac{L1 - L2}{L1(T1-T2)} \times 10^6$ (ppm /°C)
Mechanical Characteristics	Component Adhesion (Push Test)	The component shall be reflow soldered onto a P. C. Board (240°C ± 5°C for 20 seconds). Then a dynometer force gauge shall be applied to any side of the component.	1008 series ≥ 1.0kg
	Drop Test	The inductor shall be dropped two times on the concrete floor or the vinyl tile from 1m naturally.	Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Appearance: Without distinct damage
	Thermal Shock Test	Each cycle shall consist of 30 minutes at -40°C followed by 30 minutes at +85°C with 5 minutes maximum transition time between temperature extremes. Test duration is 10 cycles.	

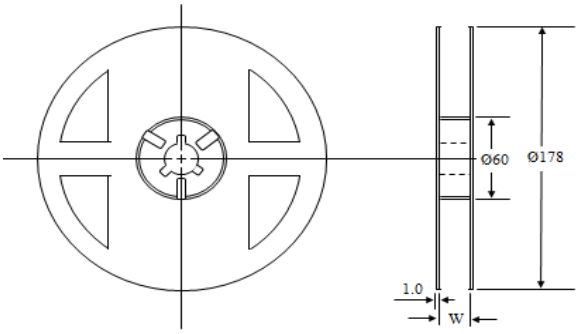
RELIABILITY TEST

ITEM		CONDITION	SPECIFICATION
Endurance Characteristics	Solderability	Dip pads in flux and dip in solder pot containing lead free solder at 240±5°C for 5 seconds.	A minimum of 80% of the metalized area must be covered with solder.
	Resistance to Soldering Heat	Dip the components into flux and dip into solder pot containing lead free solder at 260±5°C for 5±2 seconds.	Change In Inductance: No more than 5% Change In Q: No more than 10% Change In Appearance : Without distinct damage
	Vibration (Random)	Inductors shall be randomly vibrated at amplitude of 1.5mm and frequency of 10 - 55 Hz: 0.04 G / Hz for a minimum of 15 minutes per axis for each of the three axes.	
	Cold Temperature Storage	Inductors shall be stored at temperature of -40°C ± 2°C for 1000 hours (+48 -0h). Then inductors shall be subjected to standard atmospheric conditions for 1 hour. After that, measurement shall be made.	
	High Temperature Storage	Inductors shall be stored at temperature of 85°C ± 2°C for 1000 hours (+48 -0h). Then inductors shall be subjected to standard atmospheric conditions for 1 hour. After that, measurement shall be made.	
	Moisture Resistance	Inductors shall be stored in the chamber at 45°C at 90-95 R.H. for 1000 hours. Then inductors are to be tested after 2 hours at room temperature.	Inductors shall not have a shorted or open winding.
	High Temperature with Loaded	Inductors shall be stored in the chamber at 85°C for 1000 hours with rated current applied. Inductors shall be tested at the beginning of the test at 500 hours and 1000 hours. Then inductors are to be tested after 1 hour at room temperature.	

PACKING INFORMATION

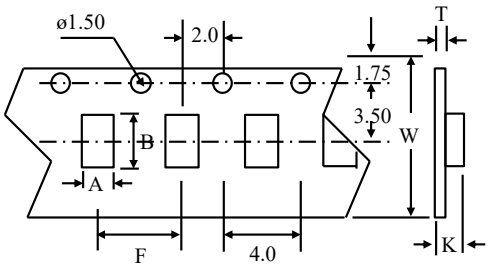
Packing Quantity

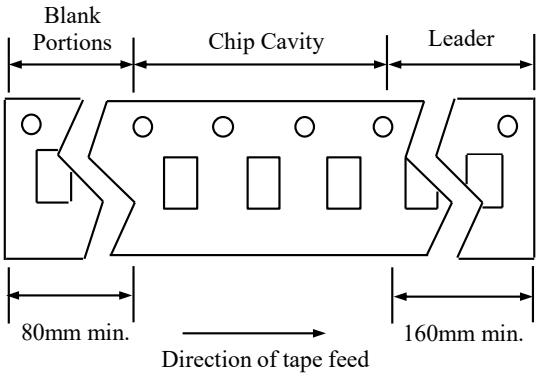
Type	Pcs / Reel
SWI1008	2,000



Dimensions (unit : mm)

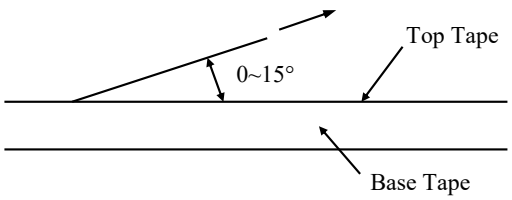
Type	Chip Cavity		Insert Pitch	Tape Thickness		W
	A	B	F	K	T	
SWI1008	2.20	2.83	4.00	1.75	0.22	8.00



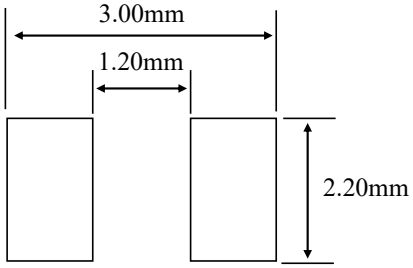


Top Tape Strength

The top tape requires a peel-off force of 0.2 to 0.7N in the direction of the arrow as illustrated below.



Recommended Pattern



SAFETY NOTES & PRECAUTION

1. Products may not be used in applications that directly affect the personal safety or cause significant impacts and losses to society. If you apply to these applications, please be sure to contact us at first to confirm.

2. The storage period is less than 12 months. Ensure to follow the storage conditions (Temperature: 5 to 30°C, Humidity: 10 to 60% RH or less). If the storage period is exceeded the limit, the electrodes might be deteriorate/ oxidized and affect soldering. Solderability should be checked if this period is exceeded.
Other storage precaution:
a) Products should be stored on the pallet for the prevention of the influence from humidity, dust and so on.
b) Products should be stored in the warehouse without heat shock, vibration, direct sunlight and so on.
c) Do not unpack the minimum package until immediately before use. After unpacking, re-seal promptly or store in deciccator with a desiccant.
d) Do not store product in bulk to prevent coils and parts being damaged.

3. Do not use or store in locations where there are corrosive gases (salt, acid, alkali, etc.).

4. Soldering condition for mounting should be within the specification range.
If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.

5. When using, try to avoid excessive mechanical impact on the product such as collision / drop…etc.

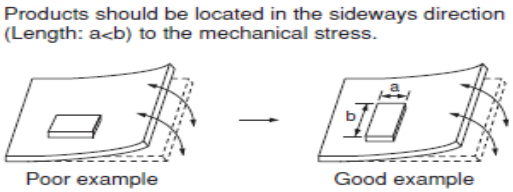
6. When assembling a printed circuit board with a new mounted chip, be careful to avoid assembly deformation of the circuit board that may cause the overall or partial distortion of the circuit board such as at screw tightening position.

7. Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the thermal design.

8. Do not expose the products to magnets or magnetic fields.

9. If you would like to use this products for more stringent safety or reliability of performance and/or quality requirements, or its failure, malfunction or trouble may cause serious damage to society, individuals or property, or you have special requirement beyond the specification or condition in the catalogue, please contact us.

10. PCB should be designed so that products are not subjected to the mechanical stress caused by warping of the board as shown below. Bending and twisting of PCB will cause excessive mechanical stress and lead to crack in the product as well.



11. Cleaning brush shall not touch the winding portion of the product to prevent the breaking of wire. Cleaning could cause failure and degradation of a product.

12. Care should be taken when transporting or handling product to avoid excessive vibration or mechanical shock. Product could be damaged by external mechanical pressure, stacked under heavy object, as well as strong shaking and drop.